IPC ASSOCIATION CON ELECTRONICS IND	Material Compos © Copyright 2005. IPC	al Composition Declaration Ight 2005. IPC, Bannockburn, Illinois. All rights reserved under both Ighan and Pan-American copyright conventions.		d under both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				s Materials and	ials and Mfg Information			
upplier In	nformation												
Company name* Compa			Company unique ID		Uni	Unique ID Authority				Response Date*			
nsemi										2023-06-08			
Contact Name Title - C			e - Contact		Pho	Phone - Contact*			Emai	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative		Pho	Phone - Representative*			Emai	Email - Representative*			
Product-Env-Stewards Pro			Product Enviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com			
Re	Requester Item Number Mfr Item		n Number Mfr Item Name		Ef	fective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
		LC87F2708AUM AH	D- 8-bit Microcont	troller	20)23-06-08				130.0	mg	Each	
lanufactu	ring Proccess Information	on											
Ter	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MSI		Rating	Peak Process Body Temperature Max Time		at Peak Tempe	erature Num	ber of Reflow Cy	cles		
contains Bi		CU Alloy	CU Alloy 4			260 C		30		conds 3			

RoHS Material Composition Declaration			Declaration Type *	Detail	led					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the					
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.5	mg	Supplier	Silicon (Si)	7440-21-3		2.4845	mg
			Supplier	Polyimide	Proprietary Data		0.0155	mg
Die Attach	0.24	mg	Supplier	Silver (Ag)	7440-22-4		0.1836	mg
			Supplier	Epoxy resins	129915-35-1		0.0564	mg
Lead Frame	16.07	mg	Supplier	Silver (Ag)	7440-22-4		0.6717	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0305	mg
			Supplier	Iron (Fe)	7439-89-6		0.4001	mg
			Supplier	Copper (Cu)	7440-50-8		14.9451	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0225	mg
Mold Compound-Black	109.14	mg		Epoxy Phenol Resin	proprietary data		12.0054	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5457	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		49.6587	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		46.9302	mg
Plating	1.72	mg	В	Bismuth (Bi)	7440-69-9		0.0103	mg
			Supplier	Tin (Sn)	7440-31-5		1.7097	mg
Wire Bond - Au	0.33	mg	Supplier	Gold (Au)	7440-57-5		0.33	mg